IPC ASSOCIATION OF ELECTRONICS I	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier l	Information													
Company name*			Company ur	Company unique ID			Unique ID Authority				Response Date*			
nsemi											2025-05-11			
ontact Nar	ne	Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*				
roduct-En	v-Stewards	Product Enviro Compliance			I	NA			Prod	Product-Env-Stewards@onsemi.com				
uthorized 1	Representative*	Title - Representative			P	Phone - Representative*			Email	Email - Representative*				
roduct-En	v-Stewards	Product Enviro Compliance			1	NA			Prod	Product-Env-Stewards@onsemi.com				
I	Requester Item Number Mi		r Item Number Mfr Item Name				Effective Date Version		Manufacturing Site		Weight*	UOM	Unit Type	
		FAM65HR51DS2 APM16-CAB SF3 650V 51mOh Al2O3 L-forming H-Bridge				n Cap	2025-05-11		СРА		12027.753	mg	Each	
Ianufact	uring Proccess Informa	tion												
Т	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		-STD-020 MSL	Rating	Peak Process Body Temperature Max Time at Peal			at Peak Temper	k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed		CU Alloy NA		NA .		0	C	30	sec	onds 3				
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RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitors Ceramic	150.0	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		43.7415	mg
			Supplier	Silver (Ag)	7440-22-4		0.396	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.078	mg
			Supplier	Tin (Sn)	7440-31-5		0.825	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.315	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		81.2355	mg
			В	Nickel (Ni)	7440-02-0		15.8715	mg
			Supplier	Copper (Cu)	7440-50-8		7.095	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.4425	mg
DBC	3280.0	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1312	mg
			В	Nickel (Ni)	7440-02-0		32.8	mg
			Supplier	Copper (Cu)	7440-50-8		1935.2	mg
Die	114.487	mg	Supplier	Silicon (Si)	7440-21-3		114.487	mg
Die Attach Solder	68.0	mg	Supplier	Silver (Ag)	7440-22-4		2.04	mg
			Supplier	Tin (Sn)	7440-31-5		65.62	mg
			Supplier	Copper (Cu)	7440-50-8		0.34	mg
Lead Frame	975.0	mg	В	Nickel (Ni)	7440-02-0		0.6825	mg
			Supplier	Iron (Fe)	7439-89-6		0.975	mg
			Supplier	Copper (Cu)	7440-50-8		973.05	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2925	mg
Mold Compound-Black	7320.0	mg	Supplier	Carbon Black (C)	1333-86-4		73.2	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6222	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1024.8	mg
Plating	50.0	mg	Supplier	Tin (Sn)	7440-31-5		50	mg
Wire Bond - Al	70.266	mg	Supplier	Aluminum (Al)	7429-90-5		70.266	mg